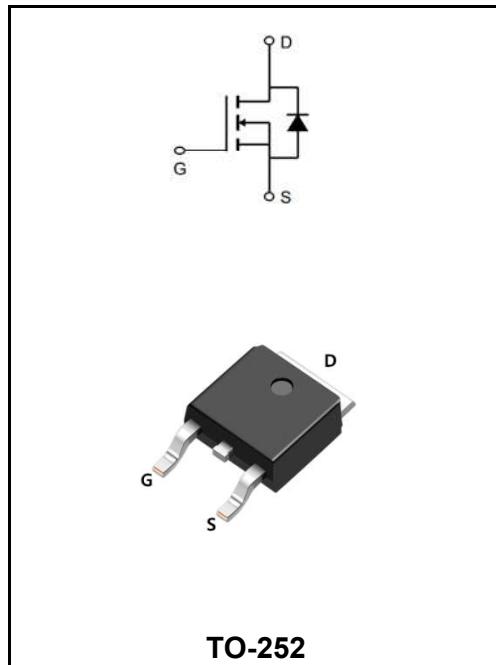


20V N-CHANNEL ENHANCEMENT MODE MOSFET
MAIN CHARACTERISTICS

I_D	20A
V_{DSS}	20V
$R_{DS(on)-typ}(@V_{GS}=10V)$	< 15mΩ (Type: 12 mΩ)


Application

- ↳ Solar road lights
- ↳ Load switch
- ↳ Uninterruptible power supply

Product Specification Classification

Part Number	Package	Marking	Pack
YFW20N02AD	TO-252	YFW 20N02AD XXXXX	2500PCS/Tape

Maximum Ratings at $T_c=25^\circ\text{C}$ unless otherwise specified

Characteristics	Symbols	Value	Units
Drain-Source Voltage	V_{DS}	20	V
Gate - Source Voltage	V_{GS}	± 20	V
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_c=25^\circ\text{C}$	I_D	20	A
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_c=100^\circ\text{C}$	I_D	13	A
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_A=25^\circ\text{C}$	I_D	6.3	A
Continuous Drain Current, $V_{GS} @ 10V^1 @ T_A=70^\circ\text{C}$	I_D	5.8	A
Pulsed Drain Current ²	I_{DM}	50	A
Single Pulse Avalanche Energy ³	E_{AS}	8.1	mJ
Avalanche Current	I_{AS}	12.7	A
Total Power Dissipation ⁴ @ $T_c=25^\circ\text{C}$	P_D	20.8	W
Total Power Dissipation ⁴ @ $T_A=25^\circ\text{C}$	P_D	2	W
Storage Temperature Range	T_{STG}	-55 to +150	°C
Operating Junction Temperature Range	T_J	-55 to +150	°C
Thermal Resistance Junction-Ambient ¹	$R_{\theta JA}$	62	°C/W
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	6	°C/W

Maximum Ratings at T_c=25°C unless otherwise specified

Characteristics	Test Condition	Symbols	Min	Typ	Max	Units
Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	BV _{DSS}	20	22	-	V
BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA	ΔBV _{DSS/ΔTJ}	-	0.018	-	V/°C
Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	V _{GS(th)}	0.5	0.65	1.0	V
Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =7.6A	R _{DS(ON)}	-	12	15	mΩ
	V _{GS} =2.5V, I _D =3.5A		-	15.5	20	
	V _{GS} =1.8V, I _D =2.5A		-	20.5	35	
Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V	I _{DSS}	-	-	1	μA
Gate - Body Leakage Current	V _{GS} =±10V, V _{DS} =0V	I _{GSS}	-	-	±100	nA
Input Capacitance	V _{DS} =10V V _{GS} =0V f=1.0MHz	C _{iss}	-	888	-	pF
Output Capacitance		C _{oss}	-	133	-	
Reverse Transfer Capacitance		C _{rss}	-	117	-	
Total Gate Charge	V _{GS} =4.5V V _{DS} =10V I _D =6.8A	Q _g	-	11.05	-	nC
Gate-Source Charge		Q _{gs}	-	1.73	-	
Gate-Drain Charge		Q _{gd}	-	3.1	-	
Turn-on delay time	V _{GS} =4.5V V _{DS} =10V I _D = 6.8A R _{GEN} = 3Ω	t _{D(on)}	-	7	-	ns
Turn-on Rise Time		T _r	-	46	-	
Turn-Off Delay Time		t _{d(OFF)}	-	30	-	
Turn- Off Fall Time		t _f	-	52	-	
Drain Forward Voltage	V _{GS} =0V , I _S =7.6A	V _{SD}	-	-	1.2	V

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The power dissipation is limited by 150°C junction temperature
4. The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation. Typical Characteristics

Ratings and Characteristic Curves

Typical Characteristics

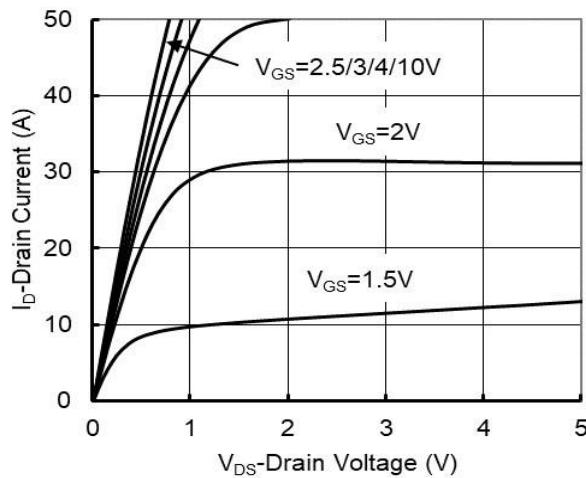


Figure 1. Output Characteristics

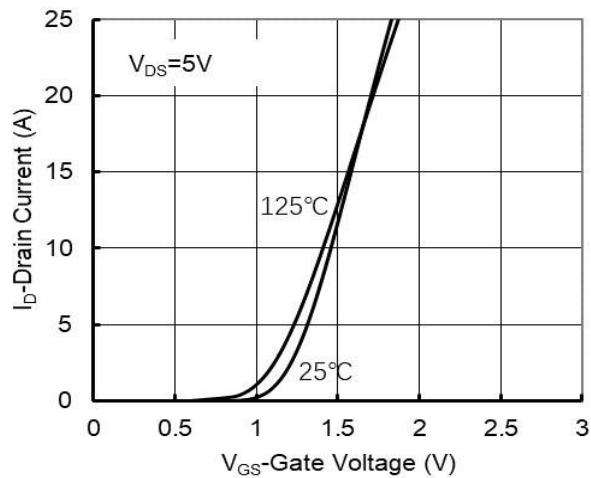


Figure 2. Transfer Characteristics

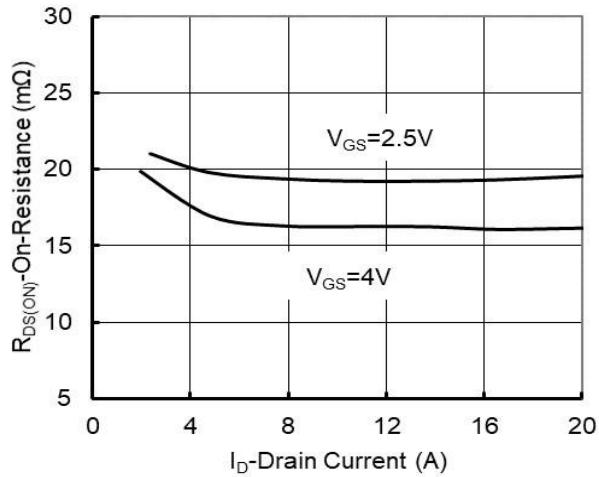


Figure 3: On-Resistance vs. Drain Current

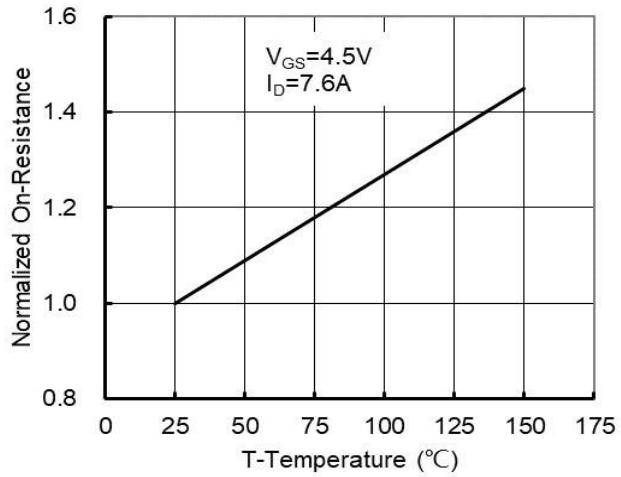


Figure 4: On-Resistance vs. Junction Temperature and Gate Voltage

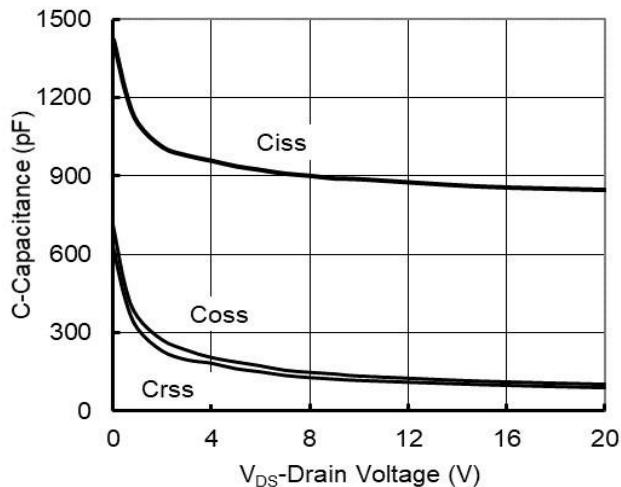


Figure 5. Capacitance Characteristics

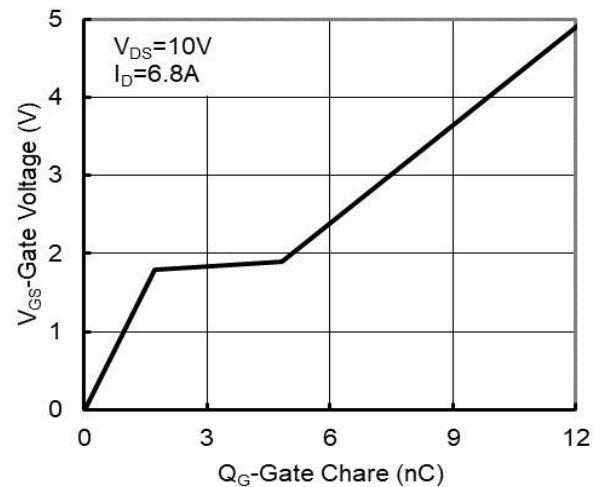


Figure 6. Gate Charge

Ratings and Characteristic Curves

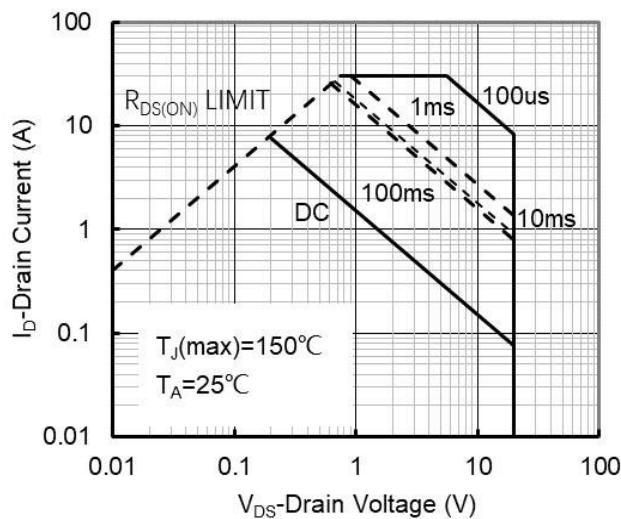


Figure7. Safe Operation Area

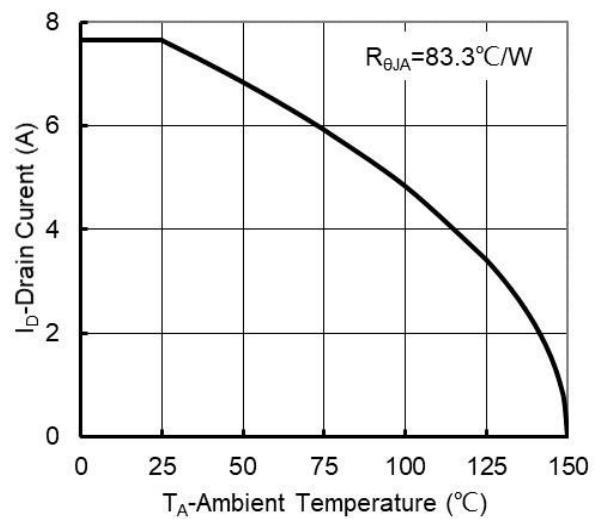


Figure8. Maximum Continuous Drain Current vs Ambient Temperature

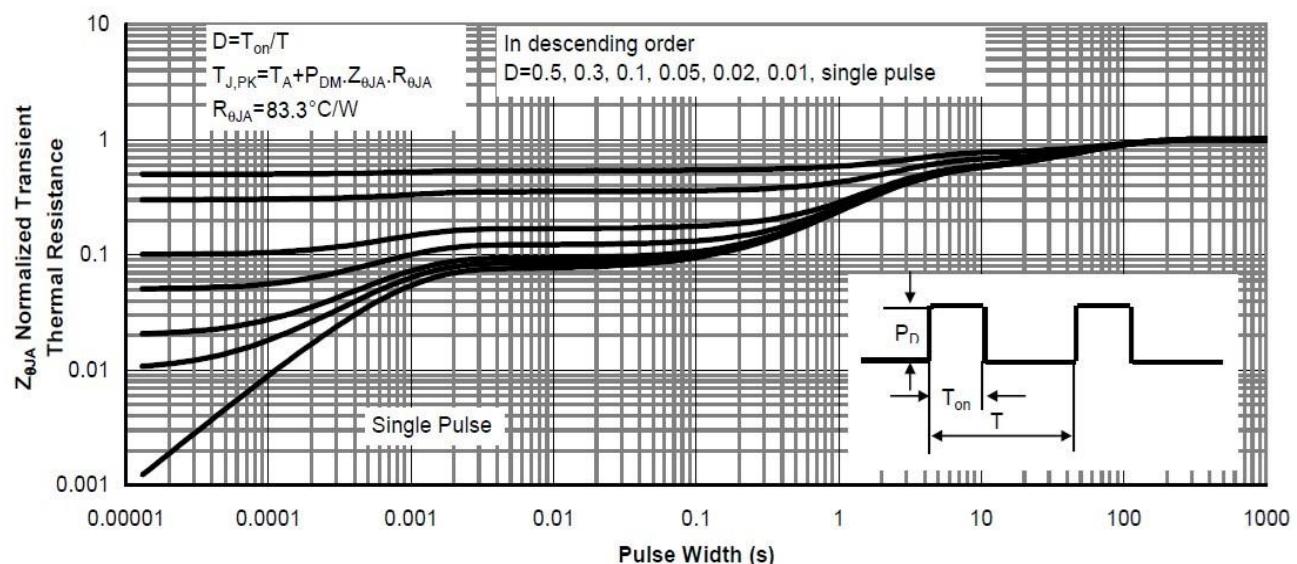
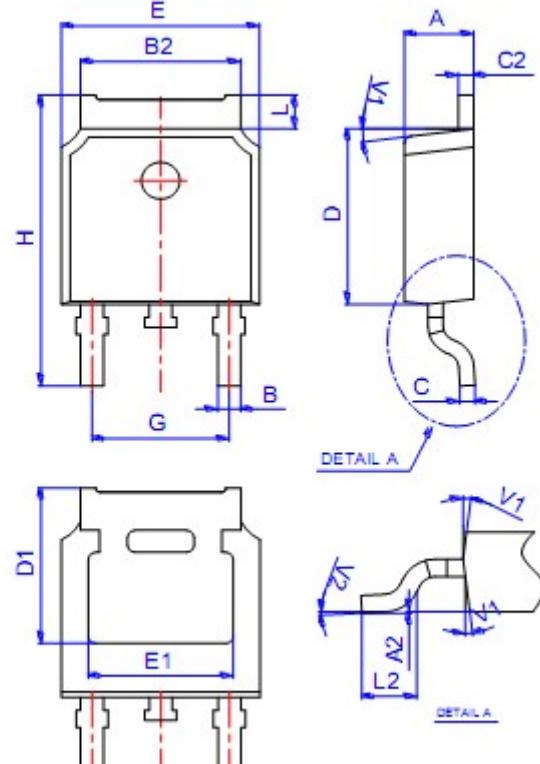


Figure9. Normalized Maximum Transient Thermal Impedance

Package Outline Dimensions Millimeters

TO-252



Dim.	Min.	Typ.	Max.
A	2.10	-	2.50
A2	0	-	0.10
B	0.66	-	0.86
B2	5.18	-	5.48
C	0.40	-	0.60
C2	0.44	-	0.58
D	5.90	-	6.30
D1	5.30REF		
E	6.40	-	6.80
E1	4.63	-	-
G	4.47	-	4.67
H	9.50	-	10.70
L	1.09	-	1.21
L2	1.35	-	1.65
V1	-	7°	-
V2	0°	-	6°

All Dimensions in millimeter